

PRIMERGY BX920 S4

System configurator and order-information guide

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Change report



PRIMERGY Server

Instructions

This document contains basic product and configuration information that will enable you to configure your system via System-Architect.

Only the tool "System-Architect" will ensure a fast and proper configuration of your PRIMERGY server or your complete PRIMERGY Rack system.

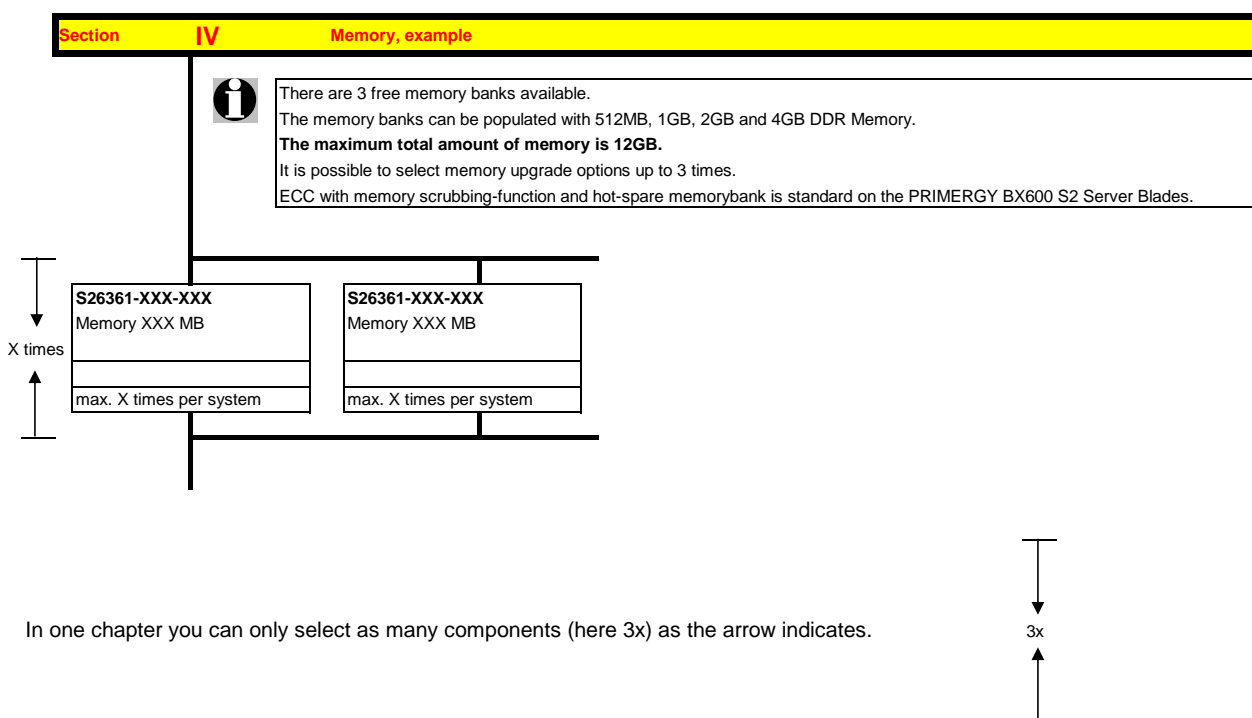
Please pay attention to the naming conventions:

BX900 S1	System unit 1nd generation
BX920 S2	Dual Server Blade S2

You can configure your individual PRIMERGY server in order to adjust your specific requirements.

The System configurator is divided into several chapters that are identical to the current price list and PC-/ System-Architect.

Please follow the lines. If there is a junction, you can choose which way or component you would like to take. Go through the configurator by following the lines from the top to the bottom.



In one chapter you can only select as many components (here 3x) as the arrow indicates.

Please note that there are information symbols which indicate necessary information.



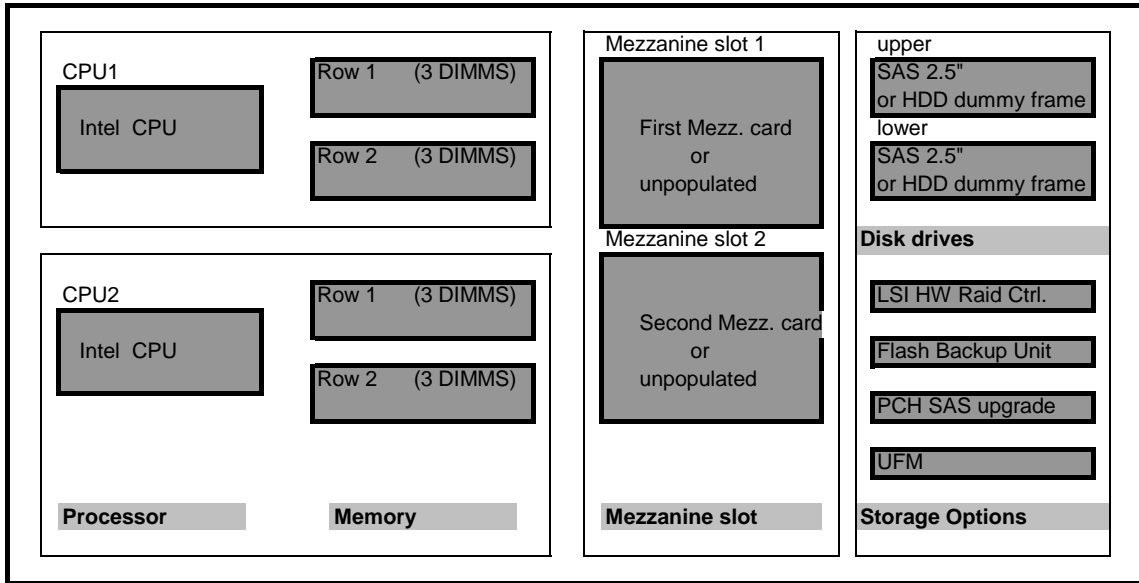
For further information see:

http://ts.fujitsu.com/products/standard_servers/index.html (internet)

https://partners.ts.fujitsu.com/com/order-supply/configurators/primergy_config/Pages/Currentconfigurators.aspx (extranet)

Prices and availability see price list and PC-/ System-Architect
 Subject to change and errors excepted

Configuration diagram Dual Server Blade BX920 S4



Key:

Included in basic unit Option

The population order for the CPU is: CPU1 first, then CPU2

The population order for the DIMMs: for each CPU, the DIMM row 1 (DIMMS 1A 1B 1C) (DIMMS 1D 1E 1F) first, then row 2 (DIMMs 2A, 2B, 2C) (DIMMs 2D, 2E, 2F)

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Section X Dual Socket Server Blade BX920 S4



Server Blade with:

- Dual INTEL Romley Processor Support as Dual/Quad/Six-Core
- The base units with INTEL Processor
- 12 DIMM sockets, organized in 2 row (6 DIMM) for CPU1 and 2 row (6 DIMM) for CPU2
- 1x Dual channel 10 Gbit Ethernet CNA controller on-board
- Hard disk controller for the 2x SAS/SATA HDD/SSD
- 2 bays for 2.5" SAS hard disks (hot-plug)
- iRMC S4 on-board
- Special connector for Y-cable (2x USB, 1x serial, 1x VGA).



Due to BE3 patent infringement delivery of S26361-K1450-V* into United States of America market is restricted.**



**The BX920 S4 Server Blade can be installed max. 18x in the BX900 System Unit
 The BX920 S4 Server Blade can be installed max. 8x in the BX400 System Unit**

S26361-K1450-V100
 PY BX920 S4 Dual Server Blade
 up to 2x 2.5" SAS/SATA hard disk drives.
 Dual Server Blade Base Unit without CPU and without memory modules!
 PY BX920 S4 Dual Server Blade
 For CPU and Memory configuration see section XLI.
 Max. 18x per BX900 System Unit.
 Max. 8x per BX400 System Unit.

S26361-F4478-L2
 PY BX900 Y-Cable frontside for KVM connection to
Server Blade
 2x USB, 1x VGA

S26361-F3552-E1
 TPM Module
 Trusted Platform Module on motherboard
 PY TPM Module
 Be aware of import restrictions!
 Max. 1x per Server Blade.

Following USB Components are available	
1) USB DVD SM / Blu-Ray	
External SuperMulti Drive (as soon as available)	S26341-F103-L119
External Blu-Ray Drive (as soon as available)	S26341-F103-L120
2) USB Keyboard:	S26381-K340-V120
KBPC PX D, professional keyboard	
3) USB Mouse:	S26381-K415-L100
Optical Wheel Mouse Tilt USB/PS2	
4) USB Memorybird:	
MyUSBS A910 8GB, MLC Flash	S26391-F6048-L208
MyUSBS A910 16GB, MLC Flash	S26391-F6048-L216

S26361-F2749-E1
 Service for Server Blade installation in the System Unit.
Hereby the BX900 S1 will be delivered completely configured and tested with Server Blades integrated.
 This order number must be in the same order as the System Unit itself.
 min. 1x per System Unit; max. 18x per System Unit; max. 1x per Server Blade

S26361-F2749-E2
 Server Blade individually packed / delivered.
The Server Blade is not built in a BX900 S1, it is separately tested and delivered.
 Contains ServerStart CD
 max. 1x per Server Blade

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Section XI Processor



There are 2 processor sockets available.
 The first socket is always equipped with the **first CPU** which can be selected via configurator
 It is also possible to upgrade a dual-processor system later on with a **second CPU**
 For the second CPU there are different order numbers, due to the different Heatsink.
Two processors with different clock frequencies are not possible
 A multi-processor operating system is required for a dual-processor system.

1x	Max. two CPU's can be selected per basic unit
	One of following CPU's has to be selected as first CPU for an orderable basic unit
	Optional second CPU has to be the same type like the first CPU
	Basic 4C CPU's
	- 1x 64-bit Intel Xeon (10MB shared TLC = Third Level Cache) 1066 MHz DDR3 Bus, 6,40 GT/s QPI Bus and passive heat sink occupies socket for one CPU
	Xeon E5-2403 v2 4C/4T 1.80GHz 10MB 6.40GT/s 1333MHz 80W S26361-F5290-E180
	Xeon E5-2407 v2 4C/4T 2.40GHz 10MB 6.40GT/s 1333MHz 80W S26361-F5290-E240
	Standard Turbo 6C CPU's
	- 1x 64-bit Intel Xeon (15/20MB shared TLC = Third Level Cache); Hyper-Threading (HT); 1333 MHz DDR3 Bus, 7,20 GT/s QPI Bus and passive heat sink occupies socket for one CPU
	Xeon E5-2420 v2 6C/12T 2.20GHz 15MB 7.20GT/s 1600MHz 80W S26361-F5290-E220
	Xeon E5-2430 v2 6C/12T 2.50GHz 15MB 7.20GT/s 1600MHz 80W S26361-F5290-E250
	Xeon E5-2440 v2 8C/16T 1.90GHz 20MB 7.20GT/s 1600MHz 95W S26361-F5290-E190
	Advanced Turbo+ 8C CPU's
	- 1x 64-bit Intel Xeon (20MB shared TLC = Third Level Cache); Hyper-Threading (HT); 1600 MHz DDR3 Bus, 8,00 GT/s QPI Bus and passive heat sink occupies socket for one CPU
	Xeon E5-2450 v2 8C/16T 2.50GHz 20MB 8.00GT/s 1600MHz 95W S26361-F5290-E251
Xeon E5-2470 v2 10C/20T 2.40GHz 25MB 8.00GT/s 1600MHz 95W S26361-F5290-E241	
Low Power 6C/8C CPU's	
- 1x 64-bit Intel Xeon (15/25MB shared TLC = Third Level Cache); Hyper-Threading (HT); 1333/1600 MHz DDR3 Bus, 7,2/8,00 GT/s QPI Bus and passive heat sink occupies socket for one CPU	
Xeon E5-2430L v2 6C/12T 2.40GHz 15MB 7.20GT/s 1600MHz 60W S26361-F5290-E242	
Xeon E5-2450L v2 10C/20T 1.70GHz 25MB 8.00GT/s 1600MHz 60W S26361-F5290-E170	

1x	Max. two CPU's can be selected per basic unit
	One of following CPU's has to be selected as second CPU for an orderable basic unit
	Optional second CPU has to be the same type like the first CPU
	Basic 4C CPU's
	- 1x 64-bit Intel Xeon (10MB shared TLC = Third Level Cache) 1066 MHz DDR3 Bus, 6,40 GT/s QPI Bus and passive heat sink occupies socket for one CPU
	Xeon E5-2403 v2 4C/4T 1.80GHz 10MB 6.40GT/s 1333MHz 80W S26361-F5291-E180
	Xeon E5-2407 v2 4C/4T 2.40GHz 10MB 6.40GT/s 1333MHz 80W S26361-F5291-E240
	Standard Turbo 6C CPU's
	- 1x 64-bit Intel Xeon (15/20MB shared TLC = Third Level Cache); Hyper-Threading (HT); 1333 MHz DDR3 Bus, 7,20 GT/s QPI Bus and passive heat sink occupies socket for one CPU
	Xeon E5-2420 v2 6C/12T 2.20GHz 15MB 7.20GT/s 1600MHz 80W S26361-F5291-E220
	Xeon E5-2430 v2 6C/12T 2.50GHz 15MB 7.20GT/s 1600MHz 80W S26361-F5291-E250
	Xeon E5-2440 v2 8C/16T 1.90GHz 20MB 7.20GT/s 1600MHz 95W S26361-F5291-E190
	Advanced Turbo+ 8C CPU's
	- 1x 64-bit Intel Xeon (20MB shared TLC = Third Level Cache); Hyper-Threading (HT); 1600 MHz DDR3 Bus, 8,00 GT/s QPI Bus and passive heat sink occupies socket for one CPU
	Xeon E5-2450 v2 8C/16T 2.50GHz 20MB 8.00GT/s 1600MHz 95W S26361-F5291-E251
Xeon E5-2470 v2 10C/20T 2.40GHz 25MB 8.00GT/s 1600MHz 95W S26361-F5291-E241	
Low Power 6C/8C CPU's	
- 1x 64-bit Intel Xeon (15/25MB shared TLC = Third Level Cache); Hyper-Threading (HT); 1333/1600 MHz DDR3 Bus, 7,2/8,00 GT/s QPI Bus and passive heat sink occupies socket for one CPU	
Xeon E5-2430L v2 6C/12T 2.40GHz 15MB 7.20GT/s 1600MHz 60W S26361-F5291-E242	
Xeon E5-2450L v2 10C/20T 1.70GHz 25MB 8.00GT/s 1600MHz 60W S26361-F5291-E170	

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Section XII Storage



Mixed configurations with ECO SATA drives and SAS drives are not allowed
 Configurations with Eco SATA can only be mixed with BC SATA HDD type
 All combinations of SSD, BC SATA and SAS are possible - but not in same logical drive (RAID array)

Both hard disks are plugged in directly connected to the onboard controller.

One UFM can be configured in addition to the Hard Disks
 Remark: UFM is part of the VMWare Embedded solution (S26361-F2341-E431)



SAS Drives require the SAS Option to enable PCH SAS connection
 or the SAS RAID Option

Solid State Disk, Mainstream Endurance*

SSD SATA 6Gb/s 2.5" with hot plug/hot replace tray (H-P)	
100GB, Mainstream Performance	S26361-F5303-E100
200GB, Mainstream Performance	S26361-F5303-E200
400GB, Mainstream Performance	S26361-F5303-E400
800GB, Mainstream Performance	S26361-F5303-E800
SSD SAS 12Gb/s 2.5" with hot plug/hot replace tray (H-P)	
200GB, Enterprise Performance	S26361-F5297-E200
400GB, Enterprise Performance	S26361-F5297-E400
800GB, Enterprise Performance	S26361-F5297-E800
1.6TB, Enterprise Performance	S26361-F5297-E160
max. 2x per system	

as soon as available
 Interface SAS12Gb/s and SAS 6Gb/s.
 SAS 12Gb/s support is not released

*) SSD Mainstream Endurance
 10DWPD over 5y

max 2x

SAS Disk Drive 2.5"

HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray	
300GB 10000rpm,<4,5ms, 8MB Cache, 512n	S26361-F5247-E130
450GB 10000rpm,<4,5ms, 8MB Cache, 512n	S26361-F5247-E145
600GB 10000rpm,<4,5ms, 8MB Cache, 512n	S26361-F5247-E160
900GB 10000rpm,<4,5ms, 8MB Cache, 512n	S26361-F5247-E190
1,2TB 10000rpm,<4,5ms, 8MB Cache, 512n	S26361-F5247-E112
146GB 15krpm,<4,5ms, 32MB Cache, 512n	S26361-F4482-E514
300GB 15krpm,<4,5ms, 32MB Cache, 512n	S26361-F4482-E530
450GB 15krpm,<4,5ms, 32MB Cache, 512n	S26361-F4482-E545
600GB 15krpm,<4,5ms, 32MB Cache, 512n	S26361-F4482-E560
500GB 7.2krpm,<9,5ms, 64MB Cache, 512n	S26361-F5228-E500
1TB 7.2krpm,<9,5ms, 64MB Cache, 512n	S26361-F5228-E100
HDD SAS 12Gb/s 2.5" with hot plug/hot replace tray	
300GB 10000rpm, 128MB Cache, 512n	S26361-F5551-E130
600GB 10000rpm, 128MB Cache, 512n	S26361-F5551-E160
900GB 10000rpm, 128MB Cache, 512n	S26361-F5551-E190
1,2TB 10000rpm, 128MB Cache, 512n	S26361-F5551-E112
1,8TB 10000rpm, 128MB Cache, 512e	S26361-F5544-E118
max. 2x per system	

SATA Disk Drive 2.5"

HDD SATA 6Gb/s 2.5" with hot plug/hot replace tray	
250GB 7.2krpm,<9,5ms, 64MB Cache, 512n	S26361-F3708-E250
500GB 7.2krpm,<9,5ms, 64MB Cache, 512n	S26361-F3708-E500
1TB 7.2krpm,<9,5ms, 64MB Cache, 512n	S26361-F3708-E100
max. 2x per system	

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Section XIII RAID Functionality on Server Blade

i The Dual Server Blade supports different RAID solutions for internal HDD's

1. PCH based RAID
2. PCH based RAID with SAS upgrade
3. SAS RAID HDD Module with LSI HW RAID w/o cache
4. SAS RAID HDD Module with LSI HW RAID w/ 512 MB Cache and optional FBU

Also the SAS BP has to be changed. It is included in the RAID Mezz HDD Connection Kit.

i Configuration Hint - Second CPU needed for SAS RAID Modules
 The SAS RAID Modules are only supported if the second CPU is installed

S26361-F3674-E1
Onboard Controller SAS upgrade
LSI
Patsburg B
RAID 0, 1 & 10
no controller cache
SAS 3Gb/sec
4 internal ports
PCIe x4
no PCI slot required
max. 1x per Server Blade

This upgrade is required to add SAS support to the PCH controller

S26361-F4531-E513
PY SAS RAID HDD Module w/ 512 MB Cache
MegaRAID
RAID level 0/1/1E/10/5/50/6/60
SAS 6Gb/sec
pluggable on the main board
PCIe Gen3 interface
4x SAS links to midplane
2x SAS links to internal HDD's
max. 1x per Server Blade

S26361-F4531-E300
PY SAS RAID HDD Module w/o Cache
MegaRAID (iMR)
RAID level 0/1/10
SAS 6Gb/sec
pluggable on the main board
PCIe Gen3 interface
4x SAS links to midplane
2x SAS links to internal HDD's
max. 1x per Server Blade

S26361-F4531-E10
RAID FBU Upgrade
Flash Backup Unit
max. 1x per Server Blade

i The SAS Expander Mezz Card must be used in order to establish the connection to the SAS CB with the PY SAS RAID HDD Module S26361-F4531-E513 or PY SAS RAID HDD Module w/o cache S26361-F4531-E300

S26361-F4531-E50
RAID HDD Module Connection Kit
2x SAS HDD BP
max. 1x per Server Blade

1 x

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Section XIV iRMC S4, Graphics

i Graphic Controller is part of the onboard Management Controller iRMC S3.
 Other graphics are not possible.

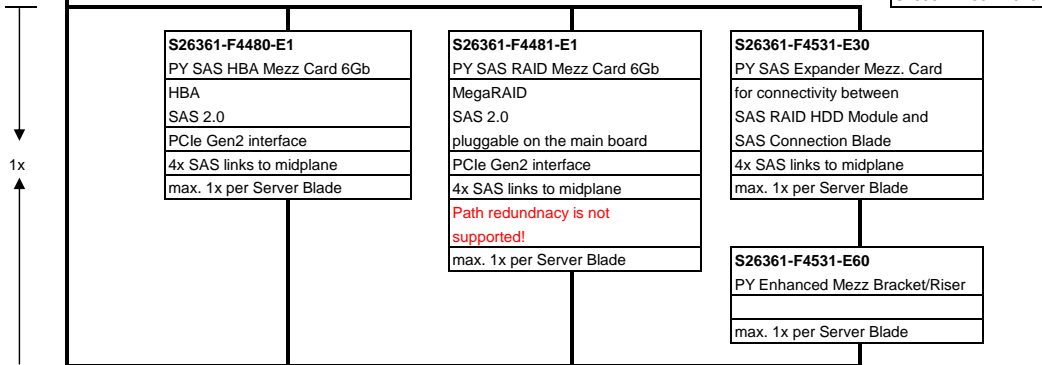
i The iRMC S4 advanced pack is included in the system delivery.
 A corresponding license order is not necessary.

Section XV Mezzanine cards for Dual Socket Server Blade

i The Dual Server Blade supports the following optional mezzanine cards.
 A Fibre Channel Switch / Pass-Thru blade, an Ethernet LAN Switch / Pass-Thru blade,
 respectively an InfiniBand switch is required in the system unit for this functionality.

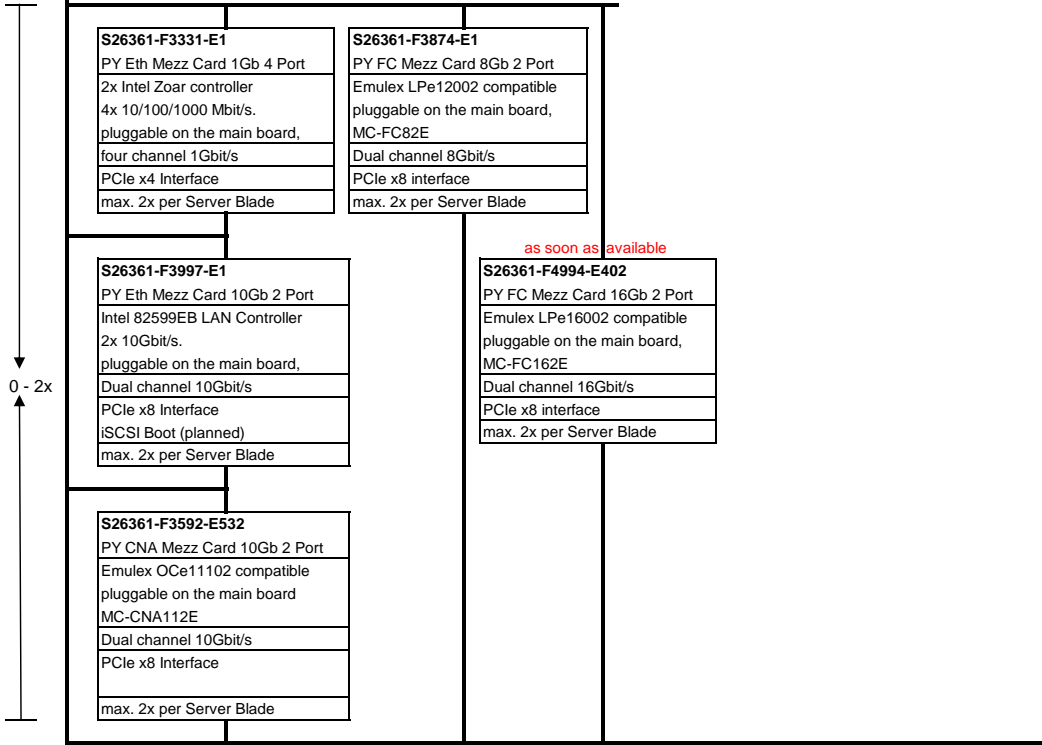
i SAS Mezz Cards require an SAS switch for each SAS link
 SAS Mezz Cards have to be installed in Mezz Card slot 2 on Server Blade

i SAS Expander Mezz Card
 can only be used with
 PY SAS RAID HDD Module
 S26361-F4531-E513



i Requires an Ethernet LAN
 Switch, IBP or Pass-Thru
 Blade for each channel.

i Requires a Fibre Channel
 Switch for each channel.



as soon as available

R S T U V

i R: see separate BX900 System Unit configurator, sheet "1 GB Ethernet"
 S: see separate BX900 System Unit configurator, sheet "10 GB Ethernet"
 T: see separate BX900 System Unit configurator, sheet "Fibre Channel"
 U: see separate BX900 System Unit configurator, sheet "InfiniBand"
 V: see separate BX900 System Unit configurator, sheet "CB SAS"
https://partners.ts.fujitsu.com/com/order-supply/configurators/primergy_config/current/Pages/default.aspx

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Section III Memory



- There are 6 memory slots per CPU for max.
 - 384GB LRDIMM (6x 64GB 8R)
 - 96GB RDIMM (6x 16GB 2R)
 - 48GB UDIMM (6x 8GB) on project release only
- => max. 768GB for two CPU's (384GB per CPU), using LRDIMM
- The memory area is divided into 3 channels per CPU with 2 slots per channel
- Slot 1 of each channel belongs to memory bank 1, slot 2 belongs to memory bank 2, slot 3 belongs to memory bank 3

Registered and Load Reduced (LR) modules can be selected
No mix of registered and load reduced modules allowed.
Memory can be operated at 1.5V or 1.35V, even if the modules are of low voltage type.
Memory operating voltage can be set within BIOS (1.5V is default setting for max. speed).
In a 2 RDIMMs per channel configuration, following frequencies are supported:

- 1.5V - 1600MHz max (depending on CPU)
- 1.35V - 1333MHz max (depending on CPU)

SDDC (Chipkill) is supported for registered & load reduced x4 organized memory modules

1.) In the "Independent Channel Mode" is following configuration possible
Channels can be populated in any order in Independent Channel Mode. All four channels may be populated in any order and have no matching requirements. All channels must run at the same interface frequency but individual channels may run at different DIMM timings (RAS latency, CAS latency, and so forth)
No mix of registered, load reduced and unbuffered modules allowed.

2.) "Rank Sparing Mode" configuration

- Within a memory channel, one rank is a spare of the other ranks.
 - The Spare Rank is held in reserve and is not available as system memory
 - For the effective memory capacity, please refer to the spreadsheet below.
 - The BIOS is set to the rank sparing setting.

Minimum configuration is: 2x 1R, 2x 2R or 1x4R DDR3 module per channel
This mode is not supported by x8 organized memory modules

3.) "Performance Mode" configuration

- In this configuration, the memory module population ex factory is spread across all channels.
- The BIOS is set to the max. performance for memory.

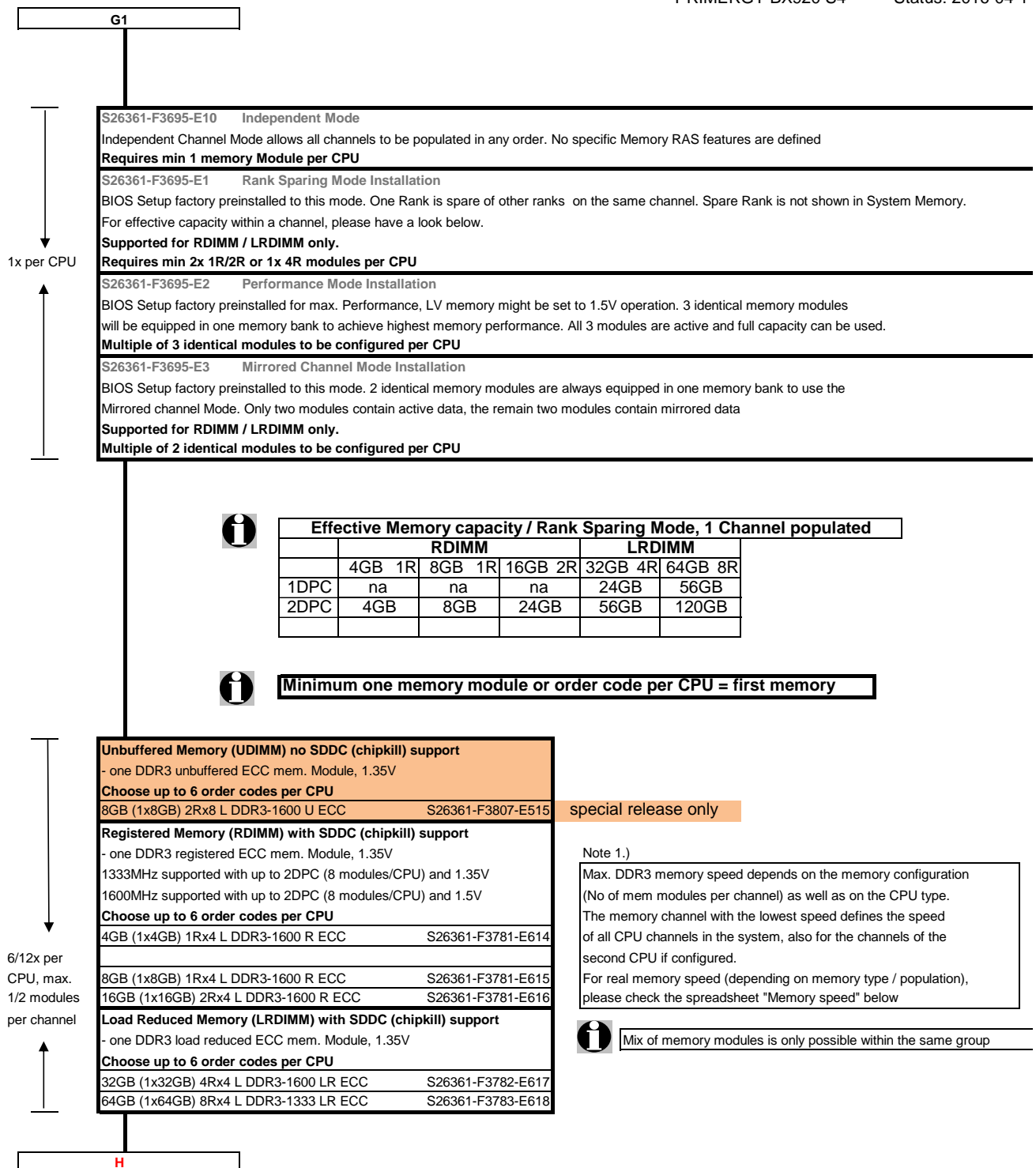
Minimum configuration is: 3x identical modules

4.) In the "Mirrored Channel Mode" is following configuration possible

- Each memory bank can optionally be equipped with 2x registered memory modules

In each memory bank channel B and C of CPU 1 or channel E and F of CPU 2 have to be equipped with identical modules for mirrored channel mode.
In channel C is always the mirrored memory of channel B of CPU 1
In channel F is always the mirrored memory of channel E of CPU 2
Minimum configuration is: 2x identical modules
This mode is not supported by x8 organized memory modules

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S26361-F3695-E10 Independent Mode
 Independent Channel Mode allows all channels to be populated in any order. No specific Memory RAS features are defined
Requires min 1 memory Module per CPU

S26361-F3695-E1 Rank Sparing Mode Installation
 BIOS Setup factory preinstalled to this mode. One Rank is spare of other ranks on the same channel. Spare Rank is not shown in System Memory.
 For effective capacity within a channel, please have a look below.
Supported for RDIMM / LRDIMM only.
Requires min 2x 1R/2R or 1x 4R modules per CPU

S26361-F3695-E2 Performance Mode Installation
 BIOS Setup factory preinstalled for max. Performance, LV memory might be set to 1.5V operation. 3 identical memory modules will be equipped in one memory bank to achieve highest memory performance. All 3 modules are active and full capacity can be used.
Multiple of 3 identical modules to be configured per CPU

S26361-F3695-E3 Mirrored Channel Mode Installation
 BIOS Setup factory preinstalled to this mode. 2 identical memory modules are always equipped in one memory bank to use the Mirrored channel Mode. Only two modules contain active data, the remain two modules contain mirrored data
Supported for RDIMM / LRDIMM only.
Multiple of 2 identical modules to be configured per CPU

Effective Memory capacity / Rank Sparing Mode, 1 Channel populated

	RDIMM			LRDIMM		
	4GB 1R	8GB 1R	16GB 2R	32GB 4R	64GB 8R	
1DPC	na	na	na	24GB	56GB	
2DPC	4GB	8GB	24GB	56GB	120GB	

Minimum one memory module or order code per CPU = first memory

Unbuffered Memory (UDIMM) no SDDC (chipkill) support
 - one DDR3 unbuffered ECC mem. Module, 1.35V
Choose up to 6 order codes per CPU

8GB (1x8GB) 2Rx8 L DDR3-1600 U ECC	S26361-F3807-E515
------------------------------------	-------------------

Registered Memory (RDIMM) with SDDC (chipkill) support
 - one DDR3 registered ECC mem. Module, 1.35V
 1333MHz supported with up to 2DPC (8 modules/CPU) and 1.35V
 1600MHz supported with up to 2DPC (8 modules/CPU) and 1.5V
Choose up to 6 order codes per CPU

4GB (1x4GB) 1Rx4 L DDR3-1600 R ECC	S26361-F3781-E614
8GB (1x8GB) 1Rx4 L DDR3-1600 R ECC	S26361-F3781-E615
16GB (1x16GB) 2Rx4 L DDR3-1600 R ECC	S26361-F3781-E616

Load Reduced Memory (LRDIMM) with SDDC (chipkill) support
 - one DDR3 load reduced ECC mem. Module, 1.35V
Choose up to 6 order codes per CPU

32GB (1x32GB) 4Rx4 L DDR3-1600 LR ECC	S26361-F3782-E617
64GB (1x64GB) 8Rx4 L DDR3-1333 LR ECC	S26361-F3783-E618

special release only

Note 1.)
 Max. DDR3 memory speed depends on the memory configuration (No of mem modules per channel) as well as on the CPU type. The memory channel with the lowest speed defines the speed of all CPU channels in the system, also for the channels of the second CPU if configured.
 For real memory speed (depending on memory type / population), please check the spreadsheet "Memory speed" below

Mix of memory modules is only possible within the same group

Memory Configuration PRIMERGY BX920 S3

Each CPU offers 6 **Slots** for DDR3 Memory Modules organised in **2 Banks and 3 Channels**.

If you need more than 6 Slots you have to configure the 2nd CPU.

Depending on the amount of memory configured you can decide between 4 basic modes of operation (see explanation below).

There are 3 different kinds of DDR3 Memory Modules available: UDIMM / RDIMM and LRDIMM

UDIMM / RDIMM / LRDIMM offer different functionality. Mix of UDIMM / RDIMM / LRDIMM is not allowed.

If 1.5V and 1.35V DIMMs are mixed, the DIMMs will run at 1.5V

Mode	Configuration	UDIMM	RDIMM	RDIMM	Application
				LRDIMM	
		x8	x8	x4	
SDDC (chipkill) support	any	no	no	yes	detect multi-bit errors
Independant Channel Mode	1, 2 or 3 Modules per Bank	no	yes	yes	offers max. flexibility, upgradeability, capacity use UDIMM modules for lowest cost
Mirrored Channel Mode *)	2 identical Modules / Bank	no	no	yes	offers maximum security
Performance Mode	3 identical Modules / Bank	no	yes	yes	offers maximum performance and capacity
Rank Sparing Mode *)	min. 2 Ranks / Channel	no	no	yes	balances security and capacity

*) For the delivery ex works the system will be prepared with dedicated BIOS setting.

Capacity	Configuration	UDIMM	RDIMM	LRDIMM	Notes
Min. Memory per CPU	1 Module / CPU	na	1x4GB	1x 16GB	with one CPU
Max. Memory per CPU	4/6 Modules / CPU	na	6x16GB	6x 32GB	with one CPU
Max. Memory per System	8/12 Modules / System	na	96GB	384GB	if second CPU is configured

Memory-Speed:

Max. DDR3 memory speed depends on the memory configuration on one memory channel and the speed of the CPU

The memory channel with the lowest speed defines the speed of all CPU channels in the system

Mem. Speed provided by CPU	Real maximum memory-bus speed depending on CPU type, memory configuration (DPC) and voltage setting (BIOS)																	
	UDIMM 1600MHz						RDIMM 1600MHz						LRDIMM 1333MHz					
	1.5V [default]			1.35V			1.5V [default]			1.35V			1.5V [default]			1.35V		
Voltage setting (BIOS)	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3
	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC
CPU with 1600MHz DDR3 Bus	1333	1333	-	1066	1066	-	1600	1600	-	1333	1333	-	1333	1333	-	1066	1066	-
CPU with 1333MHz DDR3 Bus	1333	1333	-	1066	1066	-	1333	1333	-	1333	1333	-	1333	1333	-	1066	1066	-
CPU with 1066MHz DDR3 Bus	1066	1066	-	1066	1066	-	1066	1066	-	1066	1066	-	1066	1066	-	1066	1066	-

1R - Single Rank
2R - Dual Rank
4R - Quad Rank

on special release
as soon as available

1DPC = 1 DIMM per Channel
2DPC = 2 DIMM per Channel
3DPC = 3 DIMM per Channel

Configuration hints:

- The memory sockets on the systemboard offer a color coding:

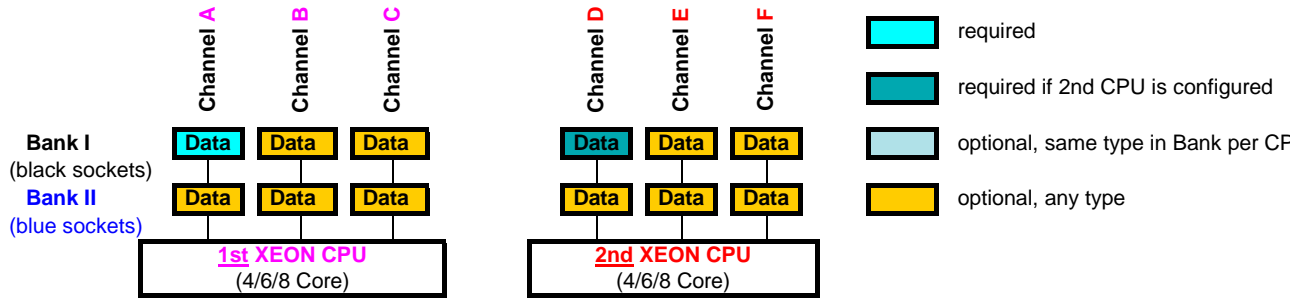
Bank I black sockets
Bank II blue sockets
Bank III green sockets

- A so called Bank consists of 1 memory module on every Channel available on one CPU (examples see below)

Bank I on CPU 1/2 up to 3 memory modules connected to Channel A - F on the 1st/2nd CPU
Bank II on CPU 1/2 up to 3 memory modules connected to Channel A - F on the 1st/2nd CPU

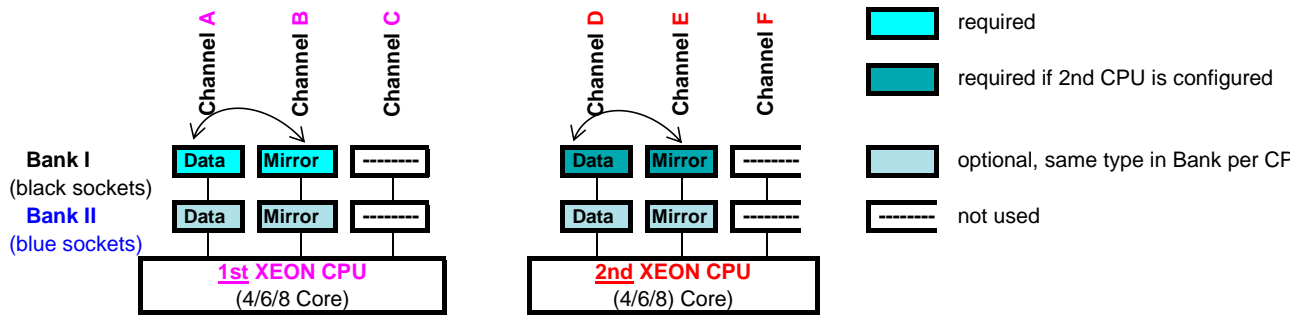
- See below and next page for a detailed descriptions of the memory configuration supported.

1. Independent Channel Mode



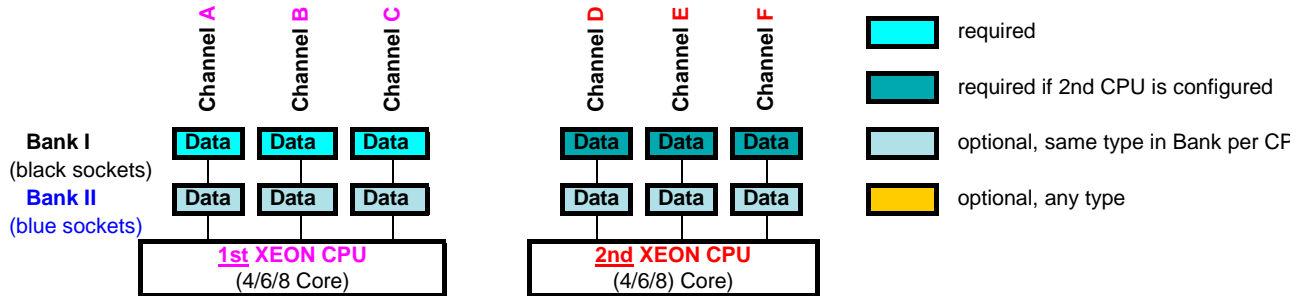
Independent Channel Mode allows all channels to be populated in any order
 Can run with differently rated DIMMs and use the settings of the slowest DIMM installed in the system

2. Mirrored Channel Mode



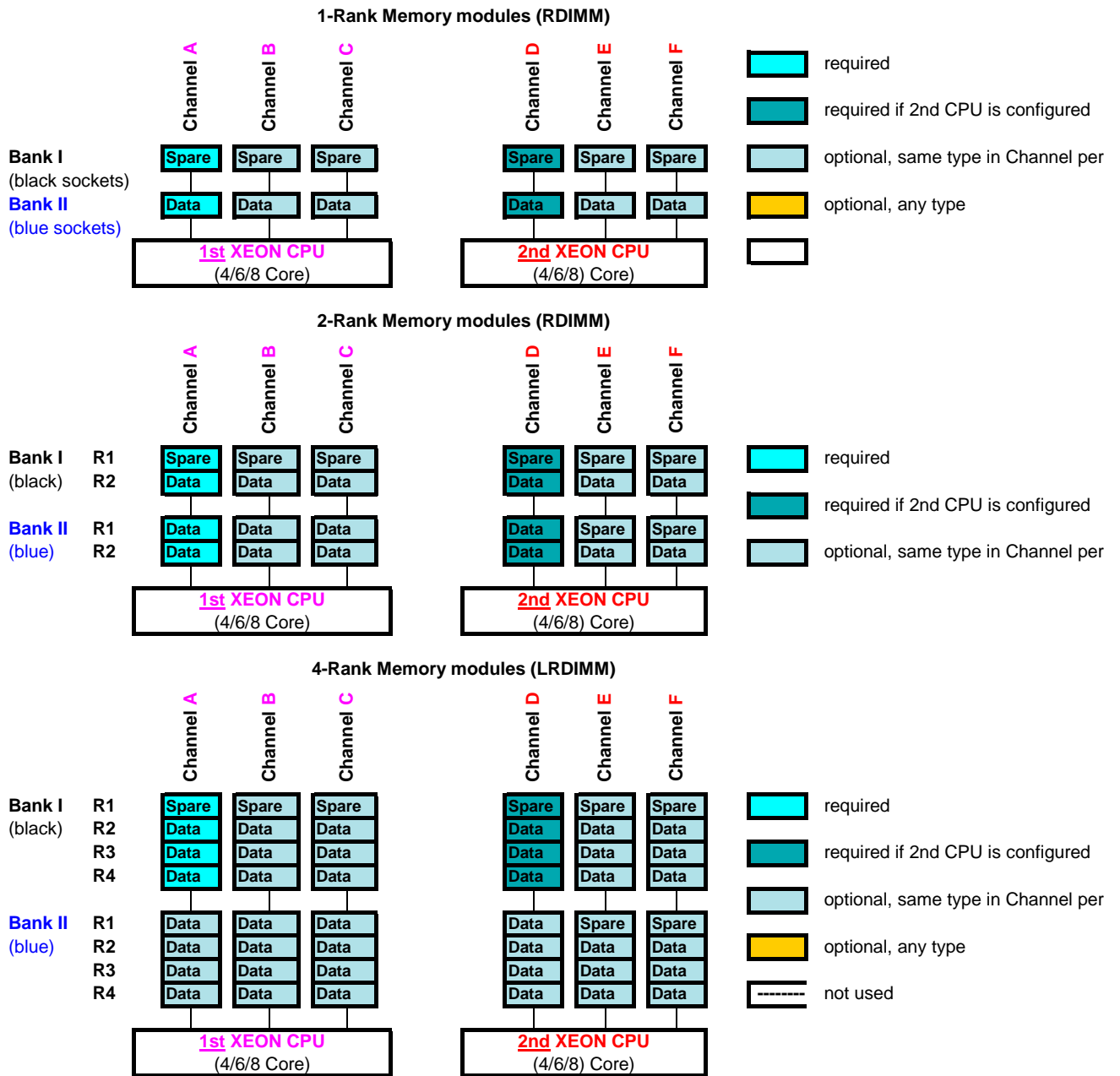
Mirrored Channel Mode requires identical modules on channel A / B (1st CPU) or channel D / E (2nd CPU)
 50% of the capacity is used for the mirror => the available memory for applications is only half of the installed memory
 If this mode is used, a multiple of 2 identical modules has to be ordered.

3. Performance Channel Mode



Performance Channel Mode requires identical modules on all channels of each Bank per CPU.
 If this mode is used, a multiple of 3 identical modules has to be ordered.

4. Rank Sparing Mode



Rank Sparing Mode requires identical modules (same capacity and technology) within the same channel.
 The available memory for applications will vary depending on configuration. Please refer to the spreadsheet above
 "Effective Memory capacity with active Rank Sparing Mode". Population rule for Rank sparing mode is to achieve max.
 available memory.

